



**Statement of Materials, Construction**

<b>LEAD-FREE -- 10L-DFN -- TABLE OF MATERIAL DECLARATION</b>								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.01054	Cu	7440-50-8	0.01027	41.94171	97.41
				Fe	7439-89-6	0.00025	1.01181	2.35
				Pb	7439-92-1	0.00000	0.01292	0.03
				P	7723-14-0	0.00001	0.03531	0.08
				Zn	7440-66-6	0.00001	0.05382	0.13
2	Die	Silicon Chip	0.00038	Si	7440-21-3	0.00038	1.54453	99.50
3	Die Attach Material	Conductive Epoxy	0.00003	Epoxy Resin	9003-36-5	0.00001	0.02451	20.00
				Silver	7440-22-4	0.00002	0.08578	70.00
				T-Butyl Phenyl Glycidyl Ether	3101-60-8	0.00000	0.00919	7.50
				Phenolic Hardener	92-88-6	0.00000	0.00184	1.50
				Butyl Cellosolve Acetate	112-07-2	0.00000	0.00123	1.00
4	Wire	Gold	0.00010	Au	7440-57-5	0.00010	0.40846	99.99
5	Lead Finish	Tin	0.00014	Sn	7440-31-5	0.00014	0.57190	100
6	Encapsulation	Epoxy Resin	0.01329	Fused Silica	60676-86-0	0.01196	48.86029	90.00
				Epoxy Resin	Proprietary	0.00066	2.71446	5.00
				Phenol Resin	Proprietary	0.00053	2.17157	4.00
				Carbon Black	1333-86-4	0.00013	0.54289	1.00
Total Package Weight			0.02448					

**Note:** Component Weight based on assembly of generic parts.

**Conclusion:**

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

Element/Compound	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%